

CALL FOR PAPERS - ABSTRACT DEADLINE EXTENDED



IEMT 2008



33rd International Electronics Manufacturing Technology Conference
4th-6th November, 2008
Parkroyal Hotel, Penang, Malaysia

ABOUT IEMT

The 33rd International Electronics Manufacturing Technology Conference (IEMT 2008) is an international event organized by the IEEE CPMT Malaysia Chapter with co-sponsorship from CPMT Santa Clara Chapter. IEMT 2008 will feature short courses, technical sessions, and exhibitions. It aims to provide good coverage of technological developments in all areas of electronics packaging, from design to manufacturing and operation. IEMT 2008 is an international forum, providing opportunities to network and meet leading experts. Since 1990's, IEMT has gained a reputation as a premier electronics materials and packaging conference and is well attended by experts in the field of electronic packaging from all over the world.

CONFERENCE TOPICS

The topics of interests are specific to electronics packaging, electronics materials, electronics manufacturing technology and reliability issues. Extended abstracts are being sought from, but not limited to, the following areas:

- Emerging Packaging Technologies
- Advanced Packaging
- Interconnection Technologies
- Manufacturing Technologies
- Surface Mount Technology
- IC Testing Technology
- Materials & Processes
- MEMS Packaging
- Electrical Modeling & Signal Integrity
- Thermal Characterization & Cooling Solutions
- Mechanical Modeling & Structural Integrity
- Quality and Reliability
- Chip-Scale Packaging/Flip Chip
- Wafer Fabrication Manufacturing

IMPORTANT DATES

Submission of Abstract 30th June, 2008
Notification of Acceptance 15th July, 2008
Submission of Manuscript 15th Sept, 2008

ABSTRACT AND PAPER SUBMISSION

Extended abstracts are invited to describe original and unpublished work. They should be about 500 words stating clearly the purpose, methodology, results, and conclusions of the work. Key references to prior publications and how the work enhances the existing knowledge should be included in the extended abstract. Authors are requested to designate appropriate areas for the purpose of abstract review. All submissions must be in English and should be made via electronic mail to conference secretariat. Author may send their abstract either in MS Word or AdobeAcrobat® PDF format with only one single file for each submission.

The abstracts must be sent to **secretariat** via email by **30th June, 2008**. Authors are requested to include their affiliation, mailing address, telephone and fax numbers, and e-mail addresses. Authors will be notified of paper acceptance and instruction for preparing final papers by **15th July 2008**. The final manuscript for publication in the conference proceedings is due by **15th September 2008**.

EXHIBITION

A 2-day tabletop exhibition from suppliers of materials, equipment, components, software, and service providers of electronics industries will be held at the venue of the conference. Potential exhibitors may email to the conference secretariat.

KEYNOTES AND SHORT COURSES

The conference will have attractive keynotes and short courses on the latest manufacturing technology and advanced packaging from experts in the field. For more details, please visit our conference website.

BEST PAPER AWARDS

Conference best paper, student best paper and best poster paper will be awarded to outstanding papers at the end of the conference. The awards will be given to the selected papers in the form of certificate and cash. Participants will also be presented with varieties of Malaysian food and cultural shows. Visit the conference website <http://cpmt.ieeemalaysia.org>

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